

ABSTRACT

The present invention relates to a maleimide resin composition containing (A) one or more selected from the group consisting of a maleimide compound having one or more N-substituted maleimide groups and a derivative thereof; and (B) a polymer having a hydrocarbon chain or a polyether chain in a main chain thereof, wherein the component (A) dissolves in an alcohol-based solvent, a ketone-based solvent, an aromatic hydrocarbon-based solvent, an ester-based solvent, or a nitrogen atom-containing solvent in an amount of 30% by mass or more at 25°C. The present invention also relates to a prepreg, a laminate, a resin film, a printed wiring board, and a semiconductor package that are obtained by using the maleimide resin composition.